

# MOSFET

## 600V CoolMOS™ P6 Power Transistor

CoolMOS™ is a revolutionary technology for high voltage power MOSFETs, designed according to the superjunction (SJ) principle and pioneered by Infineon Technologies. CoolMOS™ P6 series combines the experience of the leading SJ MOSFET supplier with high class innovation. The offered devices provide all benefits of a fast switching SJ MOSFET while not sacrificing ease of use. Extremely low switching and conduction losses make switching applications even more efficient, more compact, lighter and cooler.

### Features

- Increased MOSFET dv/dt ruggedness
- Extremely low losses due to very low FOM  $R_{DS(on)} \cdot Q_g$  and  $E_{oss}$
- Very high commutation ruggedness
- Easy to use/drive
- Pb-free plating, Halogen free mold compound

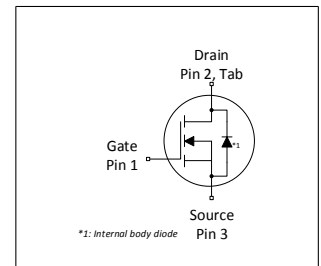
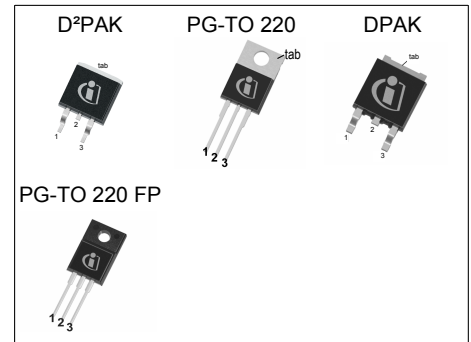
### Potential applications

PFC stages, hard switching PWM stages and resonant switching stages for e.g. PC Silverbox, Adapter, LCD & PDP TV, Lighting, Server, Telecom and UPS.

### Product validation

Fully qualified according to JEDEC for Industrial Applications

*Please note: For MOSFET paralleling the use of ferrite beads on the gate or separate totem poles is generally recommended.*



RoHS

**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	650	V
$R_{DS(on),max}$	380	mΩ
$Q_{g,typ}$	19	nC
$I_{D,pulse}$	29	A
$E_{oss@400V}$	2.7	μJ
Body diode di/dt	500	A/μs

Type / Ordering Code	Package	Marking	Related Links
IPB60R380P6	PG-TO263-3	6R380P6	see Appendix A
IPP60R380P6	PG-TO220-3		
IPD60R380P6	PG-TO252-3		
IPA60R380P6	PG-TO220 FullPAK		

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# 600V CoolMOS™ P6 Power Transistor

IPB60R380P6, IPP60R380P6, IPD60R380P6, IPA60R380P6

## 1 Maximum ratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$	-	-	10.6 6.7	A	$T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	-	-	29	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	210	mJ	$I_D=1.8\text{A}$ ; $V_{DD}=50\text{V}$ ; see table 10
Avalanche energy, repetitive	$E_{AR}$	-	-	0.32	mJ	$I_D=1.8\text{A}$ ; $V_{DD}=50\text{V}$ ; see table 10
Avalanche current, repetitive	$I_{AR}$	-	-	1.8	A	-
MOSFET dv/dt ruggedness	dv/dt	-	-	100	V/ns	$V_{DS}=0\dots400\text{V}$
Gate source voltage (static)	$V_{GS}$	-20	-	20	V	static;
Gate source voltage (dynamic)	$V_{GS}$	-30	-	30	V	AC ( $f>1\text{ Hz}$ )
Power dissipation (Non FullPAK) TO-220, TO-247	$P_{tot}$	-	-	83	W	$T_C=25^\circ\text{C}$
Power dissipation (FullPAK) TO-220FP	$P_{tot}$	-	-	31	W	$T_C=25^\circ\text{C}$
Storage temperature	$T_{stg}$	-55	-	150	$^\circ\text{C}$	-
Operating junction temperature	$T_j$	-55	-	150	$^\circ\text{C}$	-
Mounting torque (Non FullPAK) TO-220, TO-247	-	-	-	60	Ncm	M3 and M3.5 screws
Mounting torque (FullPAK) TO-220FP	-	-	-	50	Ncm	M2.5 screws
Continuous diode forward current	$I_S$	-	-	9.2	A	$T_C=25^\circ\text{C}$
Diode pulse current <sup>2)</sup>	$I_{S,pulse}$	-	-	29	A	$T_C=25^\circ\text{C}$
Reverse diode dv/dt <sup>3)</sup>	dv/dt	-	-	15	V/ns	$V_{DS}=0\dots400\text{V}$ , $I_{SD}\leq I_S$ , $T_j=25^\circ\text{C}$ see table 8
Maximum diode commutation speed	di <sub>f</sub> /dt	-	-	500	A/ $\mu\text{s}$	$V_{DS}=0\dots400\text{V}$ , $I_{SD}\leq I_S$ , $T_j=25^\circ\text{C}$ see table 8
Insulation withstand voltage for TO-220FP	$V_{ISO}$	-	-	2500	V	$V_{rms}$ , $T_C=25^\circ\text{C}$ , $t=1\text{ min}$

<sup>1)</sup> Limited by  $T_{j,max}$ . Maximum duty cycle  $D=0.75$

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup> Identical low side and high side switch with identical  $R_G$

## 2 Thermal characteristics

**Table 3 Thermal characteristics (Non FullPAK) TO-220, TO-247**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.5	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	62	°C/W	leaded
Soldering temperature, wavesoldering only allowed at leads	$T_{sold}$	-	-	260	°C	1.6mm (0.063 in.) from case for 10s

**Table 4 Thermal characteristics (FullPAK) TO-220FP**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	4	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	80	°C/W	leaded
Soldering temperature, wavesoldering only allowed at leads	$T_{sold}$	-	-	260	°C	1.6mm (0.063 in.) from case for 10s

**Table 5 Thermal characteristics TO-252**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.5	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	62	°C/W	device on PCB, minimal footprint
Thermal resistance, junction - ambient for SMD version	$R_{thJA}$	-	35	45	°C/W	Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm <sup>2</sup> (one layer, 70µm thickness) copper area for drain connection and cooling. PCB is vertical without air stream cooling.
Soldering temperature, wave & reflow soldering allowed	$T_{sold}$	-	-	260	°C	reflow MSL1

### 3 Electrical characteristics

at  $T_j=25^\circ\text{C}$ , unless otherwise specified

**Table 6 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	600	-	-	V	$V_{GS}=0V, I_D=1mA$
Gate threshold voltage	$V_{(GS)th}$	3.5	4.0	4.5	V	$V_{DS}=V_{GS}, I_D=0.32mA$
Zero gate voltage drain current	$I_{DSS}$	-	-	1	$\mu\text{A}$	$V_{DS}=600, V_{GS}=0V, T_j=25^\circ\text{C}$ $V_{DS}=600, V_{GS}=0V, T_j=150^\circ\text{C}$
Gate-source leakage current	$I_{GSS}$	-	-	100	nA	$V_{GS}=20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	0.342 0.889	0.380 -	$\Omega$	$V_{GS}=10V, I_D=3.8A, T_j=25^\circ\text{C}$ $V_{GS}=10V, I_D=3.8A, T_j=150^\circ\text{C}$
Gate resistance	$R_G$	-	7.8	-	$\Omega$	$f=1\text{MHz}$ , open drain

**Table 7 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$	-	877	-	pF	$V_{GS}=0V, V_{DS}=100V, f=1\text{MHz}$
Output capacitance	$C_{oss}$	-	42	-	pF	$V_{GS}=0V, V_{DS}=100V, f=1\text{MHz}$
Effective output capacitance, energy related <sup>1)</sup>	$C_{o(er)}$	-	33	-	pF	$V_{GS}=0V, V_{DS}=0\dots400V$
Effective output capacitance, time related <sup>2)</sup>	$C_{o(tr)}$	-	135	-	pF	$I_D=\text{constant}, V_{GS}=0V, V_{DS}=0\dots400V$
Turn-on delay time	$t_{d(on)}$	-	12	-	ns	$V_{DD}=400V, V_{GS}=13V, I_D=4.8A,$ $R_G=3.4\Omega$ ; see table 9
Rise time	$t_r$	-	6	-	ns	$V_{DD}=400V, V_{GS}=13V, I_D=4.8A,$ $R_G=3.4\Omega$ ; see table 9
Turn-off delay time	$t_{d(off)}$	-	33	-	ns	$V_{DD}=400V, V_{GS}=13V, I_D=4.8A,$ $R_G=3.4\Omega$ ; see table 9
Fall time	$t_f$	-	7	-	ns	$V_{DD}=400V, V_{GS}=13V, I_D=4.8A,$ $R_G=3.4\Omega$ ; see table 9

**Table 8 Gate charge characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{GS}$	-	5.4	-	nC	$V_{DD}=400V, I_D=4.8A, V_{GS}=0$ to 10V
Gate to drain charge	$Q_{gd}$	-	7	-	nC	$V_{DD}=400V, I_D=4.8A, V_{GS}=0$ to 10V
Gate charge total	$Q_g$	-	19	-	nC	$V_{DD}=400V, I_D=4.8A, V_{GS}=0$ to 10V
Gate plateau voltage	$V_{plateau}$	-	6.1	-	V	$V_{DD}=400V, I_D=4.8A, V_{GS}=0$ to 10V

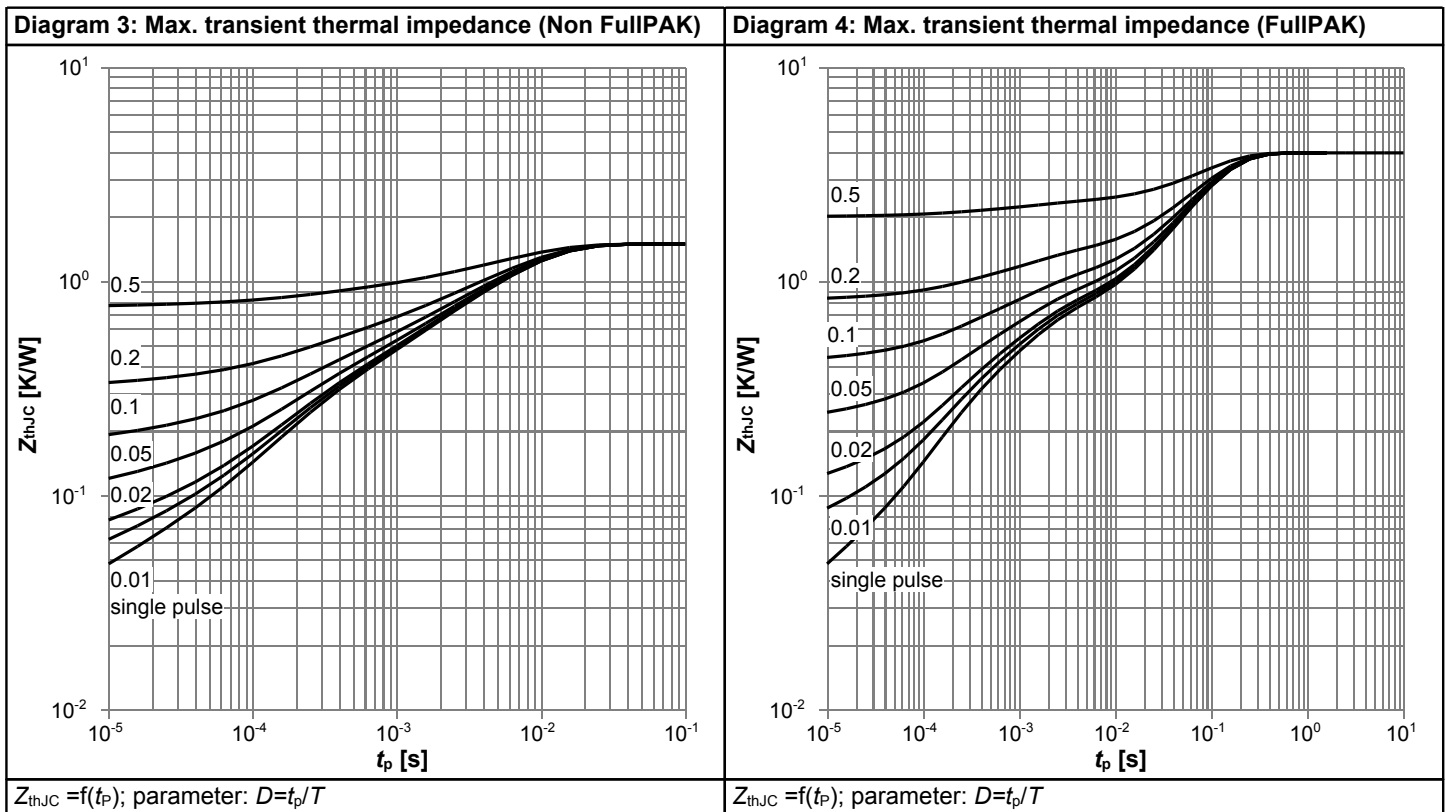
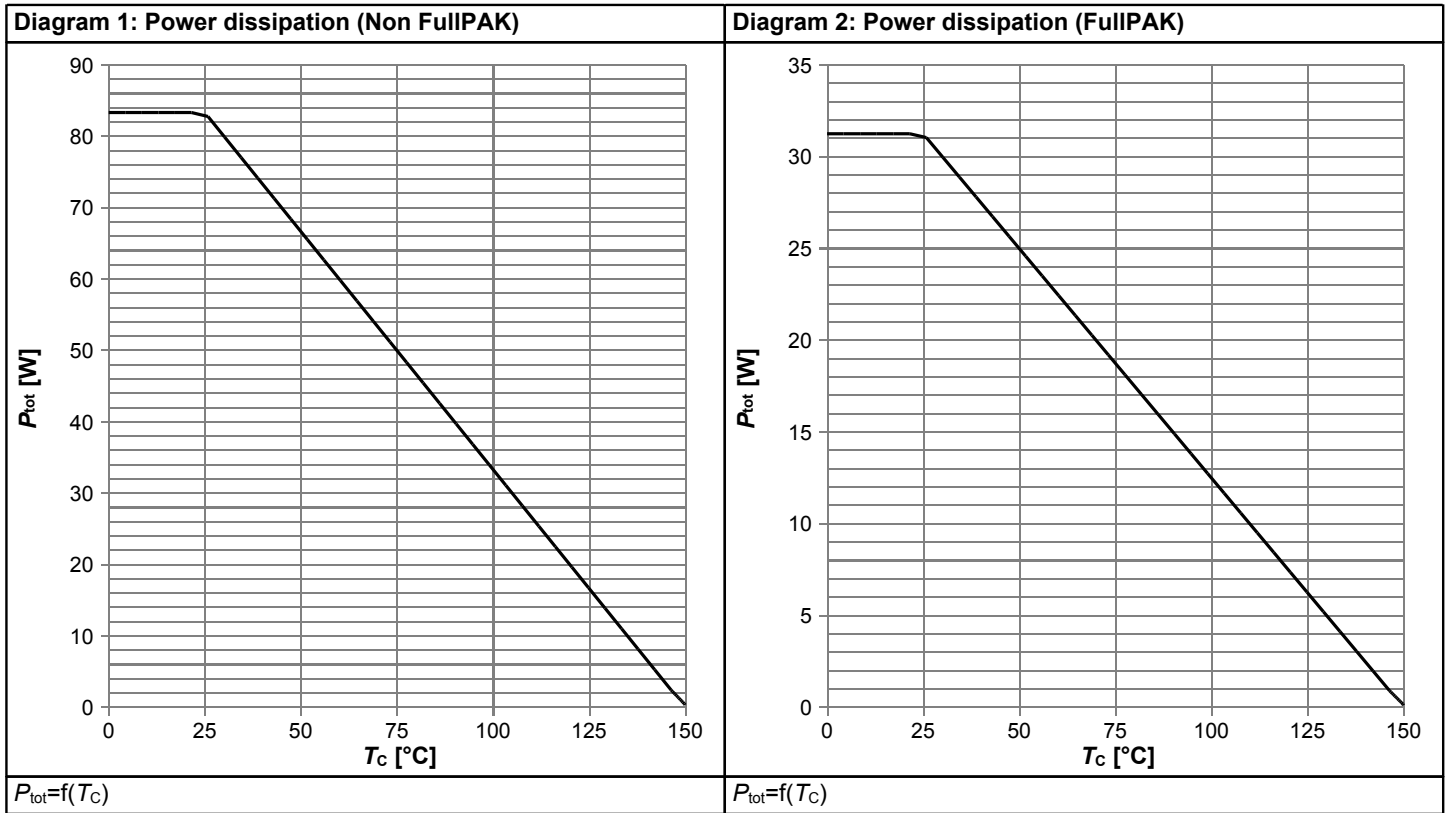
<sup>1)</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 400V

<sup>2)</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 400V

**Table 9 Reverse diode characteristics**

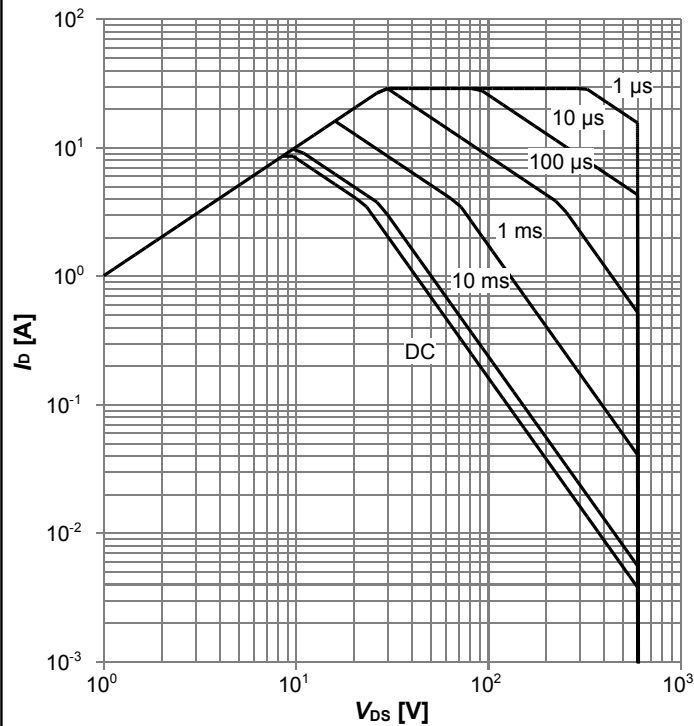
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$	-	0.9	-	V	$V_{GS}=0V, I_F=4.8A, T_j=25^\circ C$
Reverse recovery time	$t_{rr}$	-	232	-	ns	$V_R=400V, I_F=4.8A, di_F/dt=100A/\mu s$ ; see table 8
Reverse recovery charge	$Q_{rr}$	-	2.1	-	$\mu C$	$V_R=400V, I_F=4.8A, di_F/dt=100A/\mu s$ ; see table 8
Peak reverse recovery current	$I_{rrm}$	-	17	-	A	$V_R=400V, I_F=4.8A, di_F/dt=100A/\mu s$ ; see table 8

## 4 Electrical characteristics diagrams



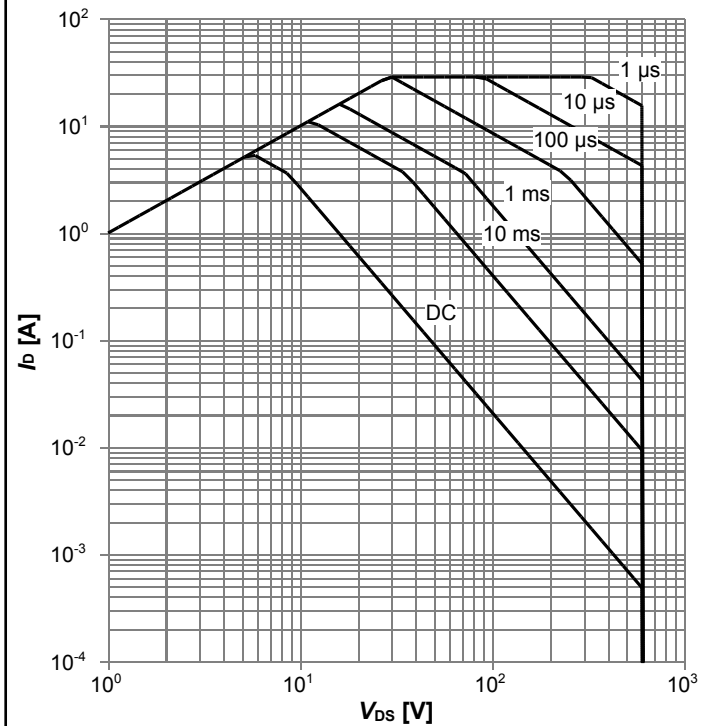
**600V CoolMOS™ P6 Power Transistor**  
 IPB60R380P6, IPP60R380P6, IPD60R380P6, IPA60R380P6

**Diagram 5: Safe operating area (Non FullIPAK)**



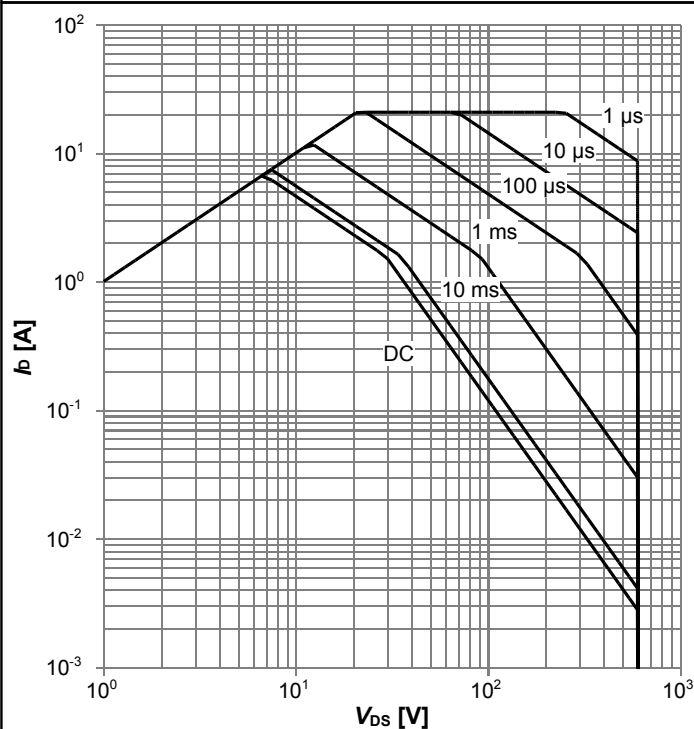
$I_D=f(V_{DS}); T_C=25\text{ °C}; D=0; \text{parameter: } t_p$

**Diagram 6: Safe operating area (FullIPAK)**



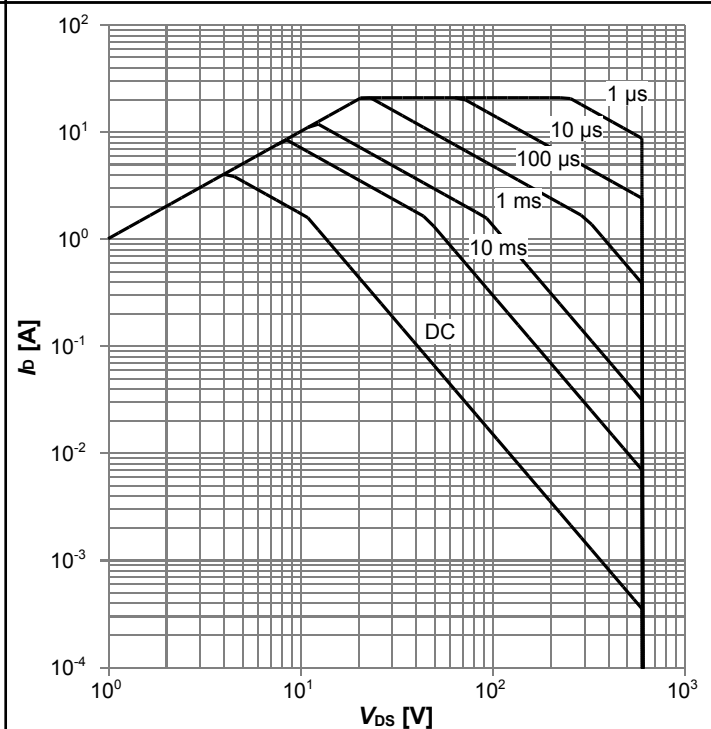
$I_D=f(V_{DS}); T_C=25\text{ °C}; D=0; \text{parameter: } t_p$

**Diagram 7: Safe operating area (Non FullIPAK)**



$I_D=f(V_{DS}); T_C=80\text{ °C}; D=0; \text{parameter: } t_p$

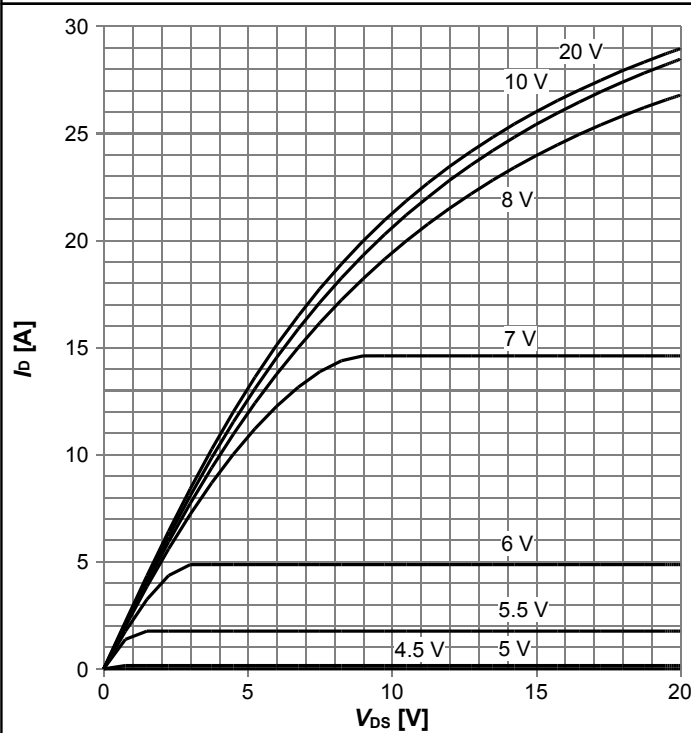
**Diagram 8: Safe operating area (FullIPAK)**



$I_D=f(V_{DS}); T_C=80\text{ °C}; D=0; \text{parameter: } t_p$

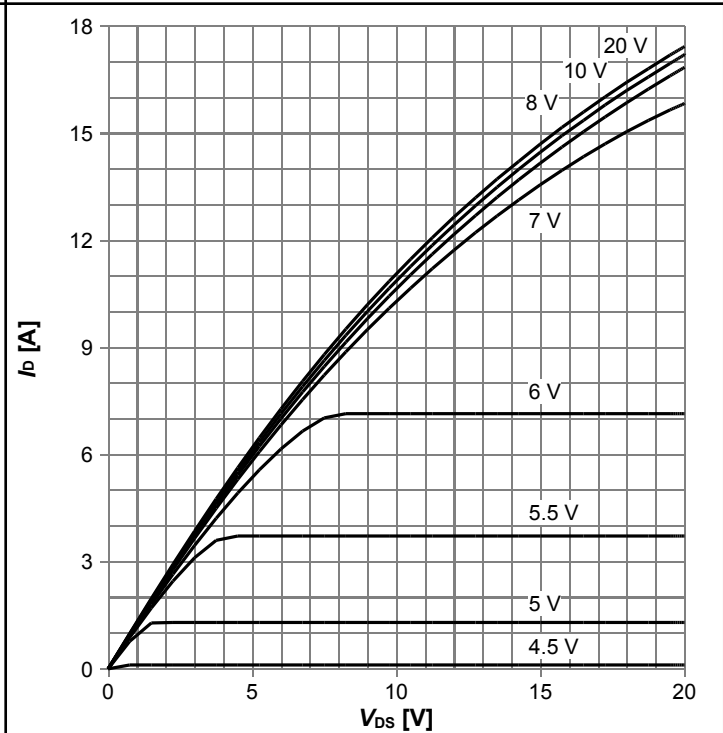
**600V CoolMOS™ P6 Power Transistor**  
**IPB60R380P6, IPP60R380P6, IPD60R380P6, IPA60R380P6**

**Diagram 9: Typ. output characteristics**



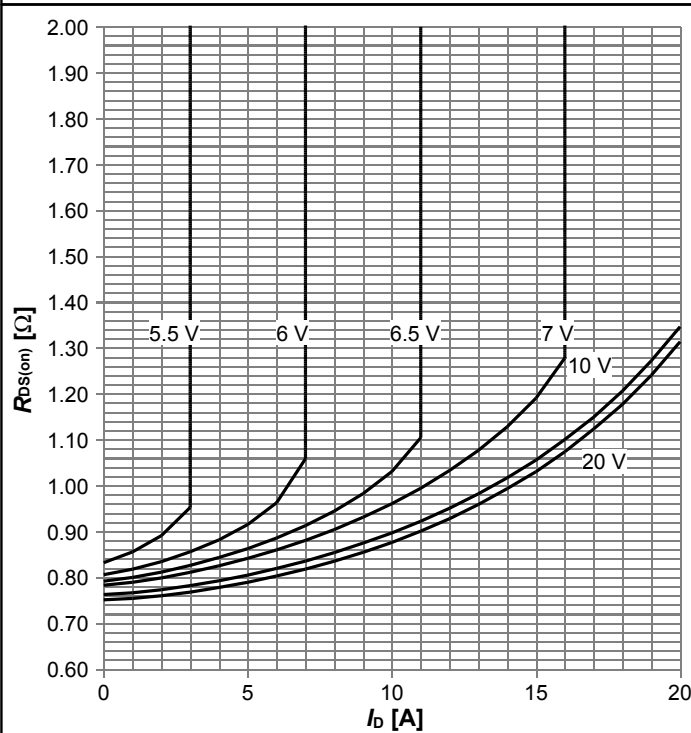
$I_D=f(V_{DS}); T_j=25\text{ }^\circ\text{C};$  parameter:  $V_{GS}$

**Diagram 10: Typ. output characteristics**



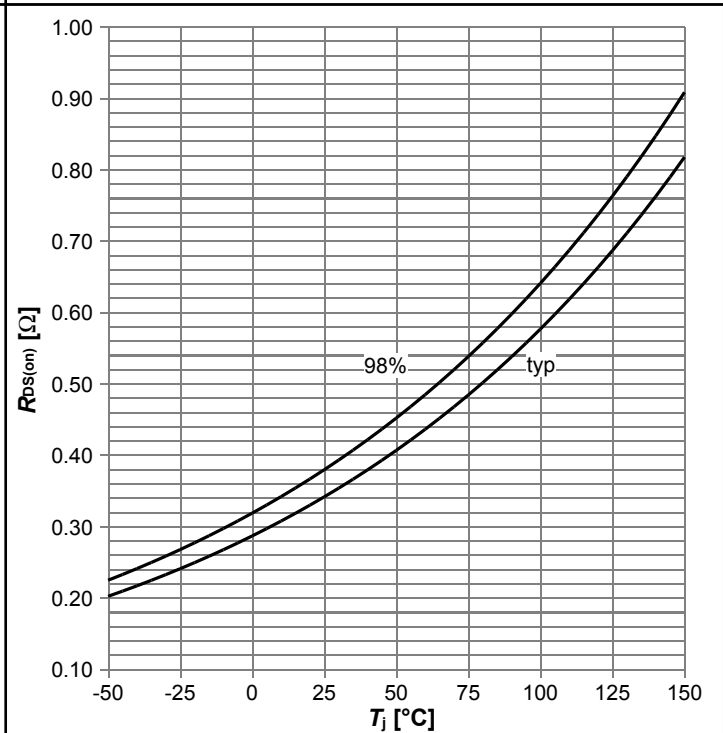
$I_D=f(V_{DS}); T_j=125\text{ }^\circ\text{C};$  parameter:  $V_{GS}$

**Diagram 11: Typ. drain-source on-state resistance**



$R_{DS(on)}=f(I_D); T_j=125\text{ }^\circ\text{C};$  parameter:  $V_{GS}$

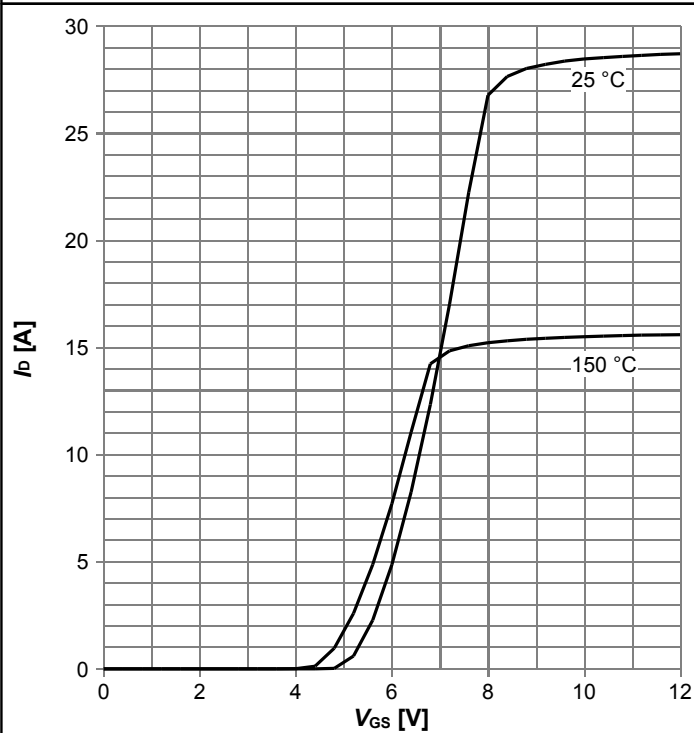
**Diagram 12: Drain-source on-state resistance**



$R_{DS(on)}=f(T_j); I_D=3.8\text{ A}; V_{GS}=10\text{ V}$

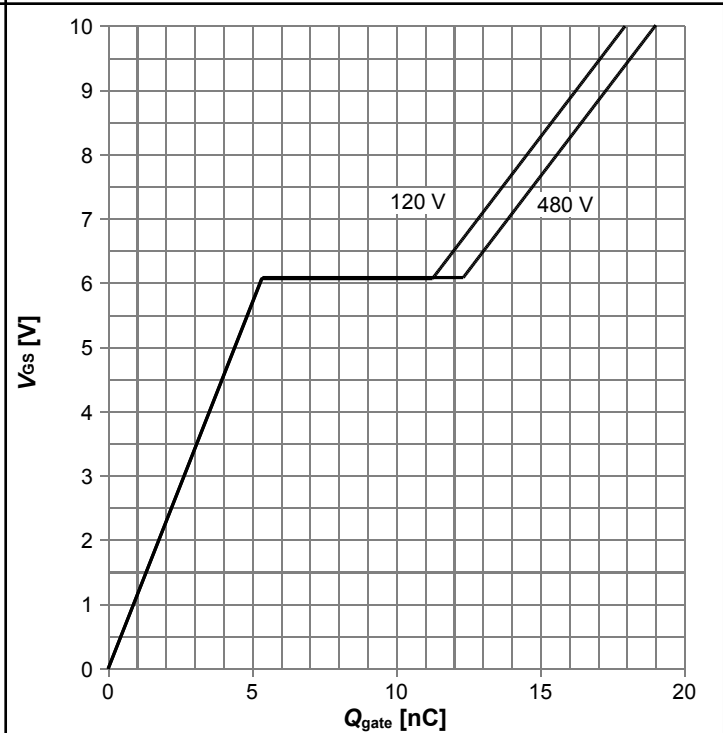
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**Diagram 13: Typ. transfer characteristics**



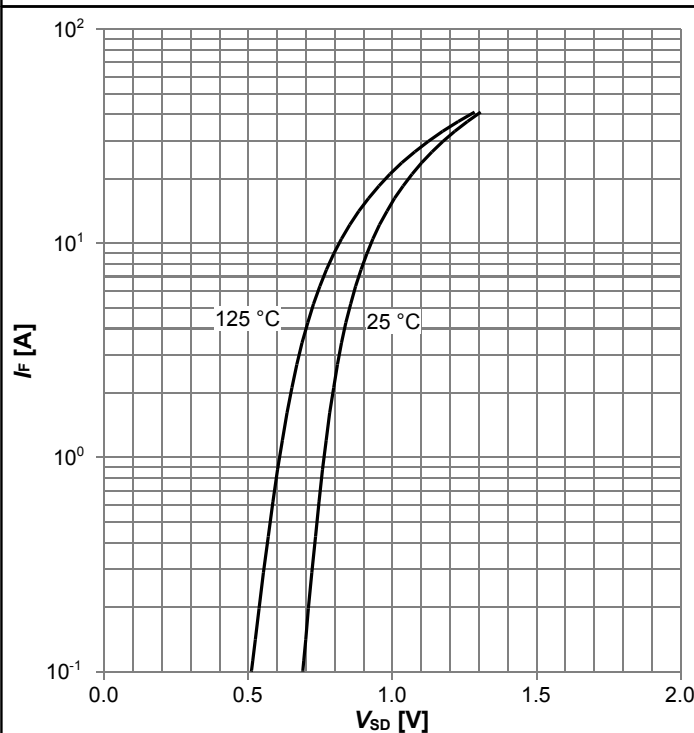
$I_D=f(V_{GS})$ ;  $V_{DS}=20V$ ; parameter:  $T_j$

**Diagram 14: Typ. gate charge**



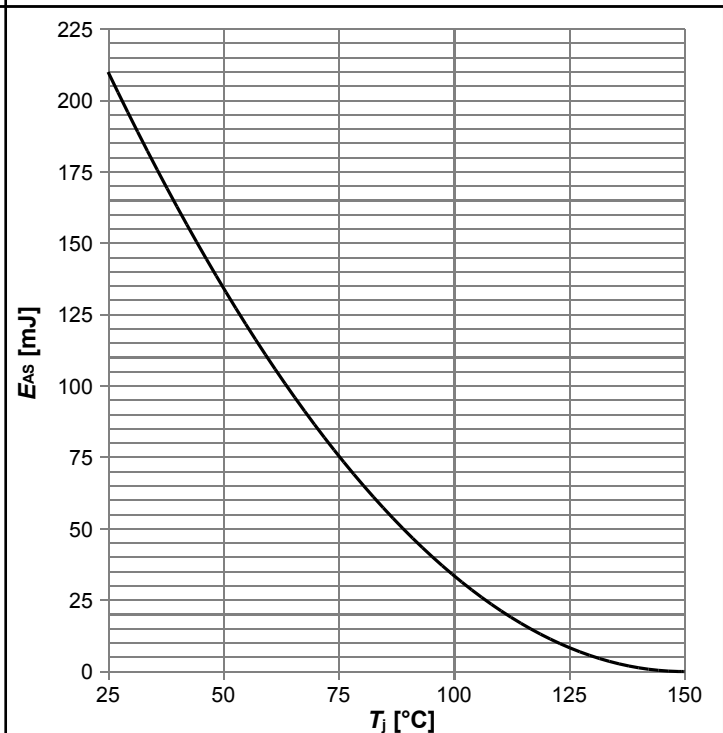
$V_{GS}=f(Q_{gate})$ ;  $I_D=4.8$  A pulsed; parameter:  $V_{DD}$

**Diagram 15: Forward characteristics of reverse diode**



$I_F=f(V_{SD})$ ; parameter:  $T_j$

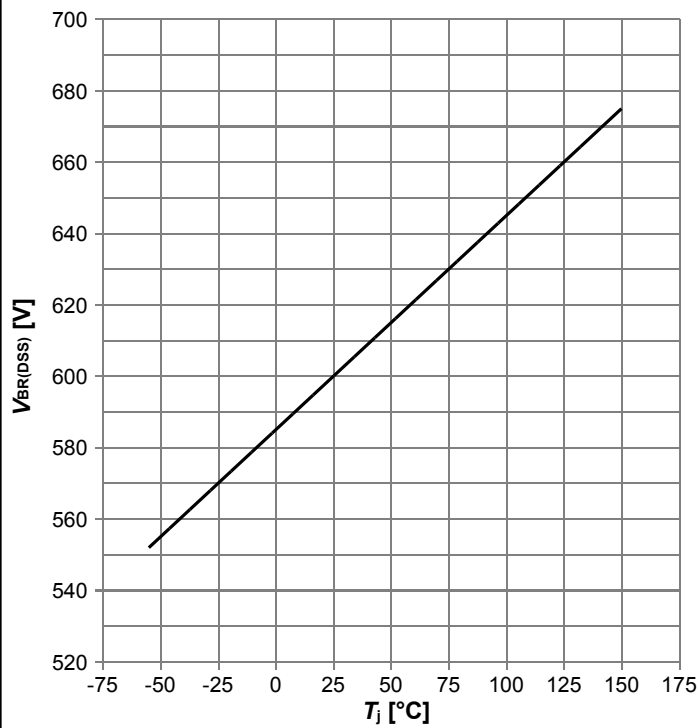
**Diagram 16: Avalanche energy**



$E_{AS}=f(T_j)$ ;  $I_D=1.8$  A;  $V_{DD}=50$  V

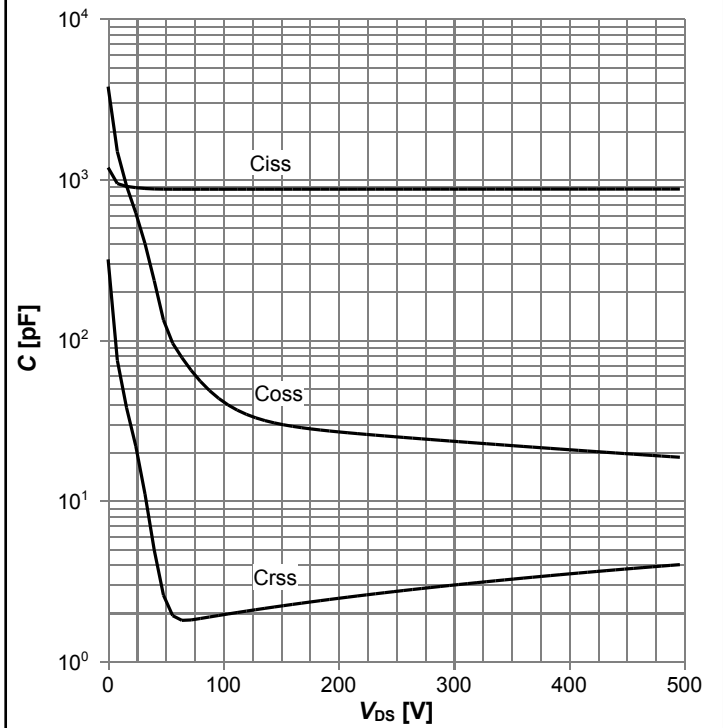
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**Diagram 17: Drain-source breakdown voltage**



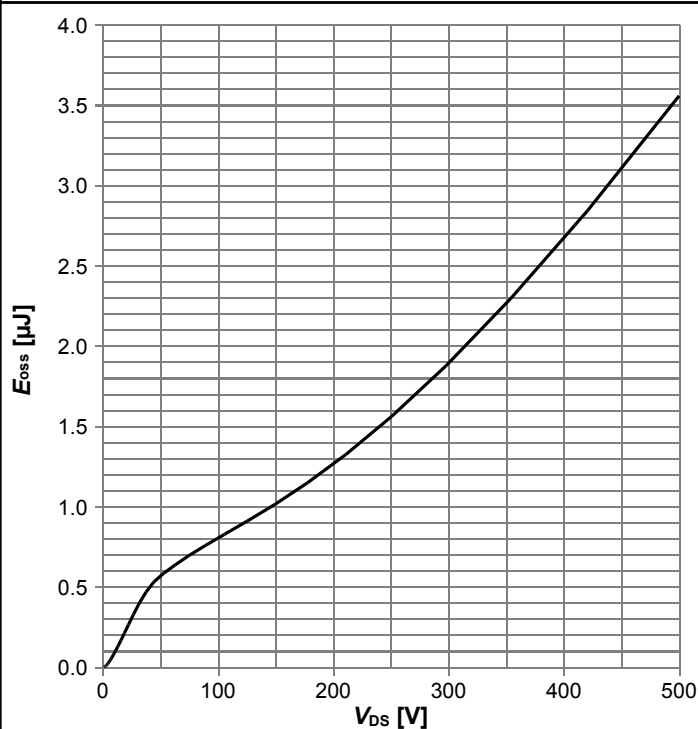
$V_{BR(DSS)}=f(T_j); I_D=1\text{ mA}$

**Diagram 18: Typ. capacitances**



$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}$

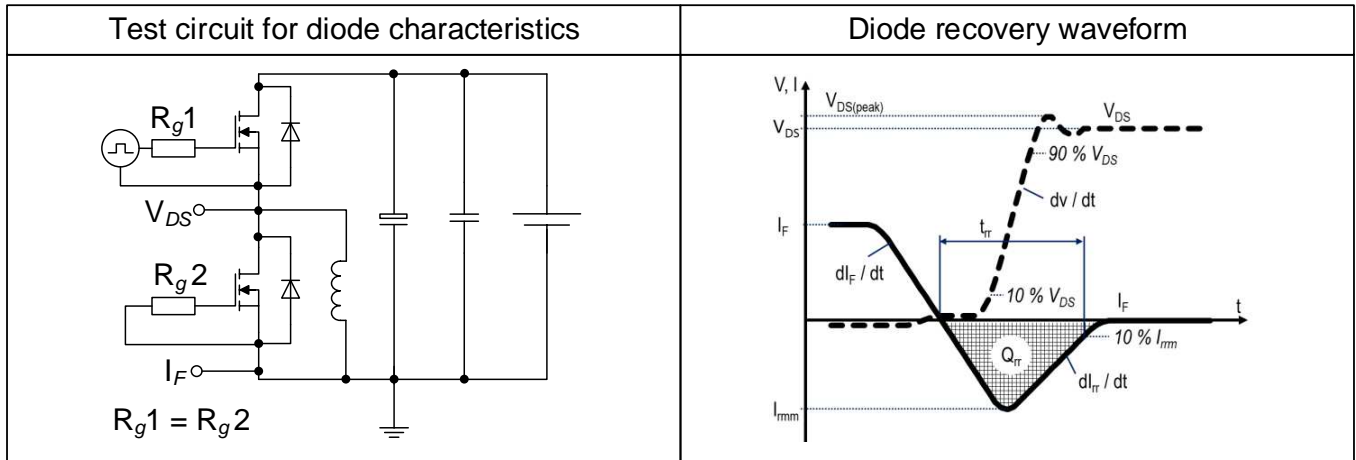
**Diagram 19: Typ. Coss stored energy**



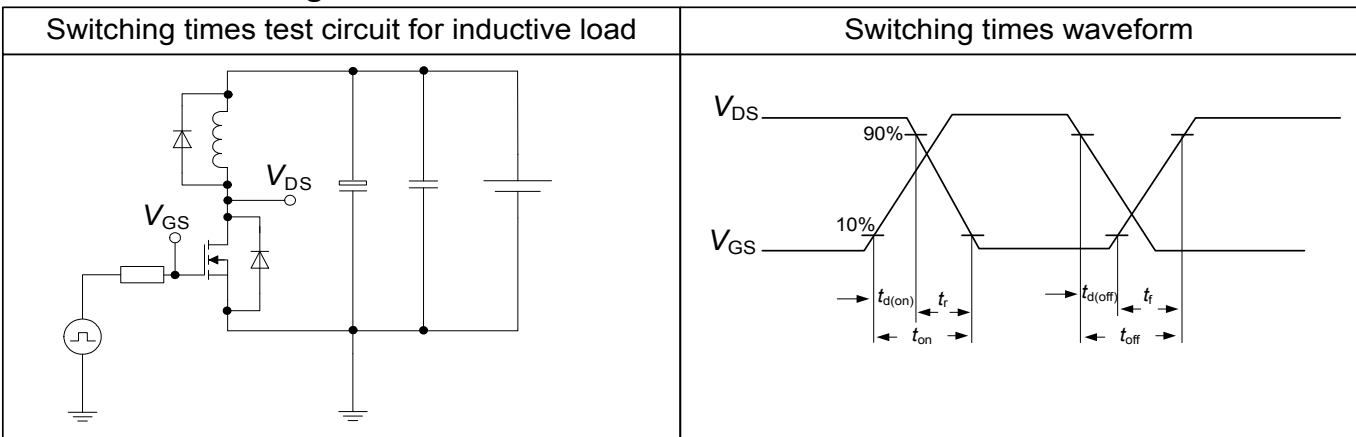
$E_{oss}=f(V_{DS})$

## 5 Test Circuits

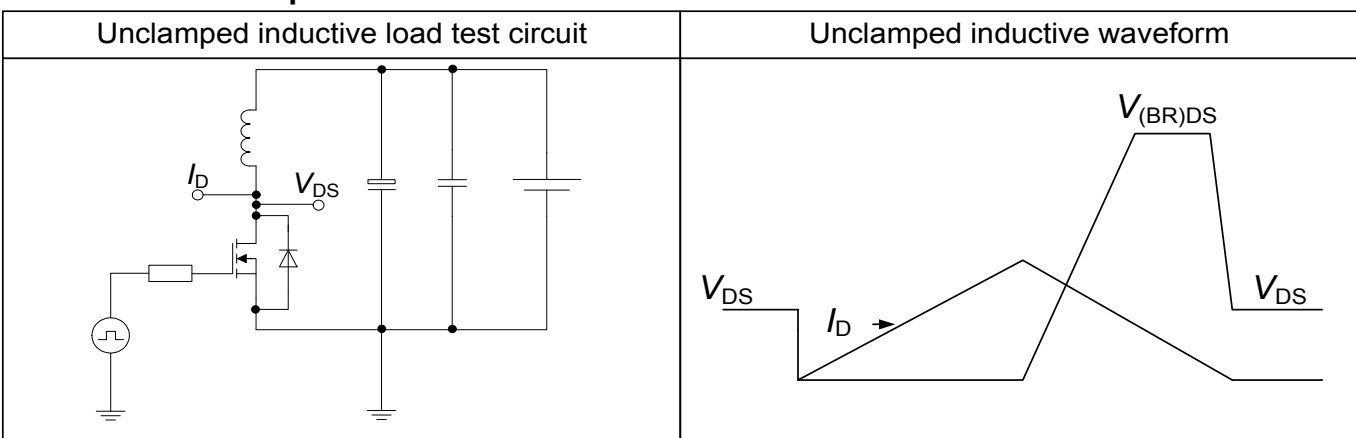
**Table 10 Diode characteristics**



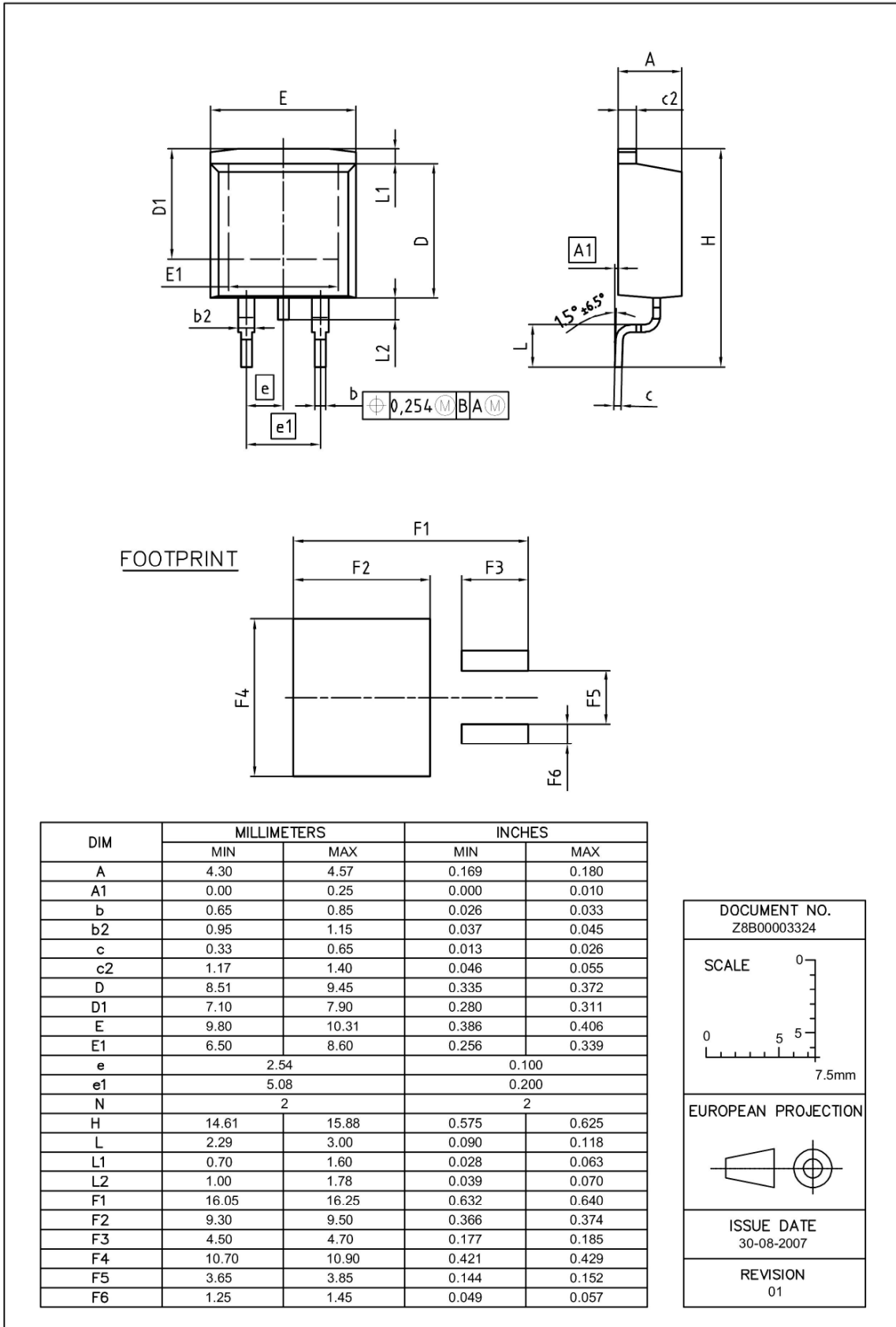
**Table 11 Switching times**



**Table 12 Unclamped inductive load**

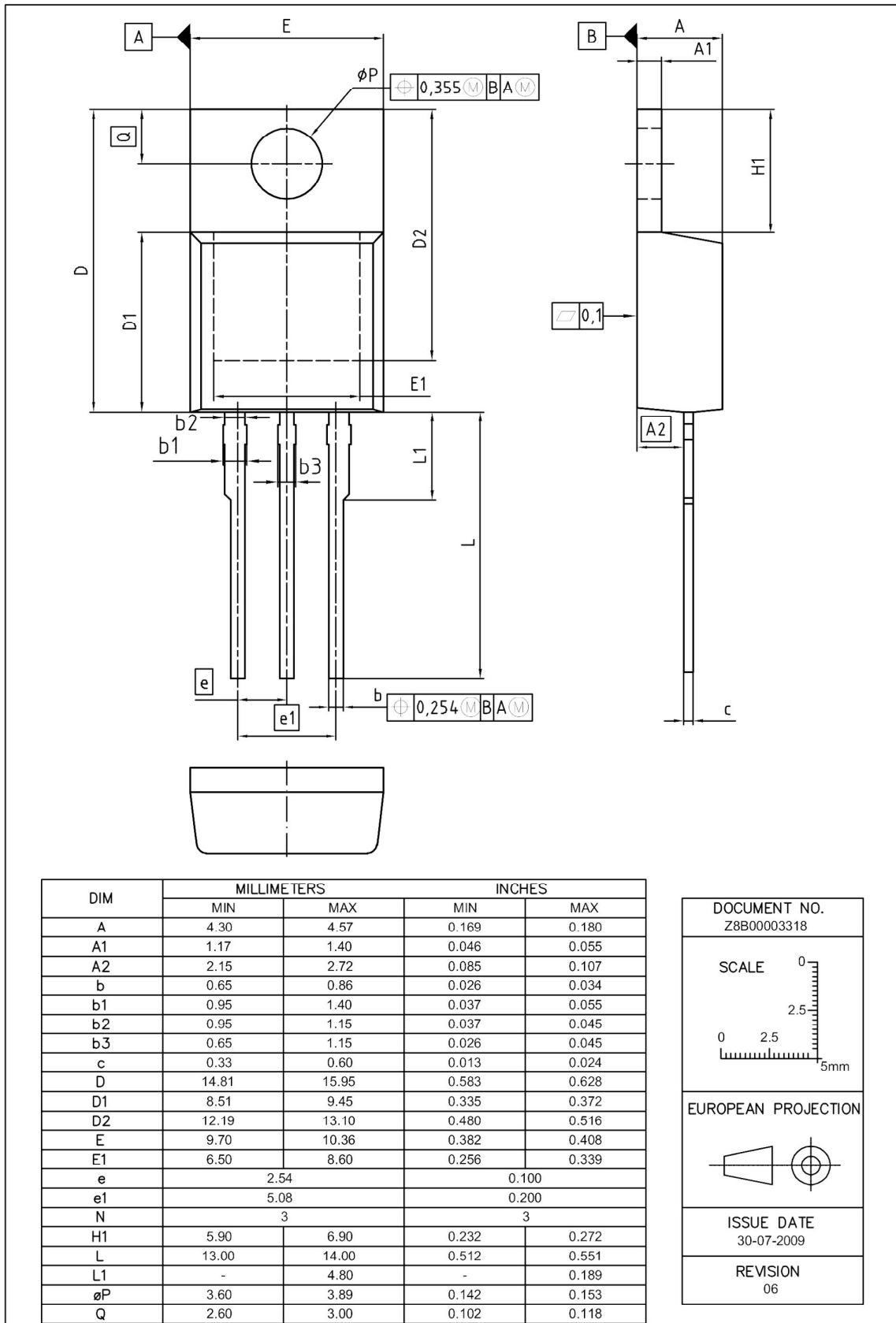


## 6 Package Outlines



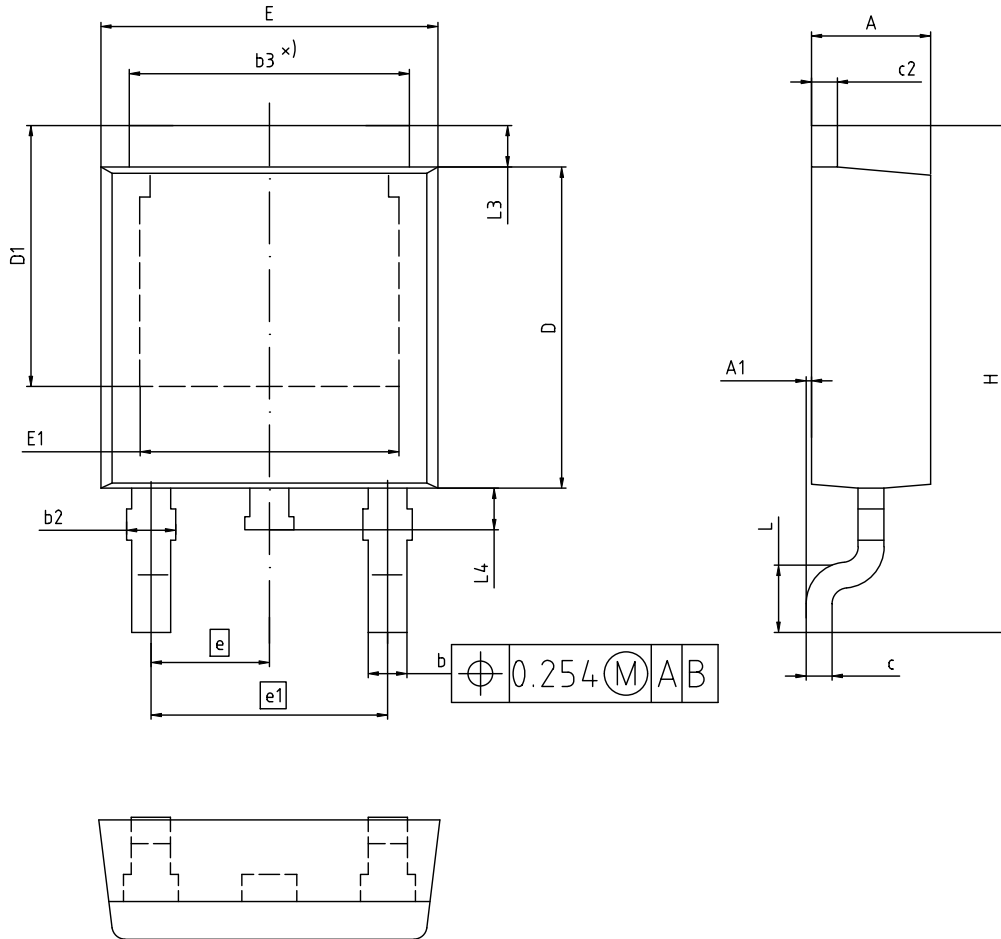
**Figure 1 Outline PG-TO263-3, dimensions in mm/inches**

**600V CoolMOS™ P6 Power Transistor**  
**IPB60R380P6, IPP60R380P6, IPD60R380P6, IPA60R380P6**



**Figure 2 Outline PG-T0220-3, dimensions in mm/inches**

**PG-TO252-3 (DPAK)**



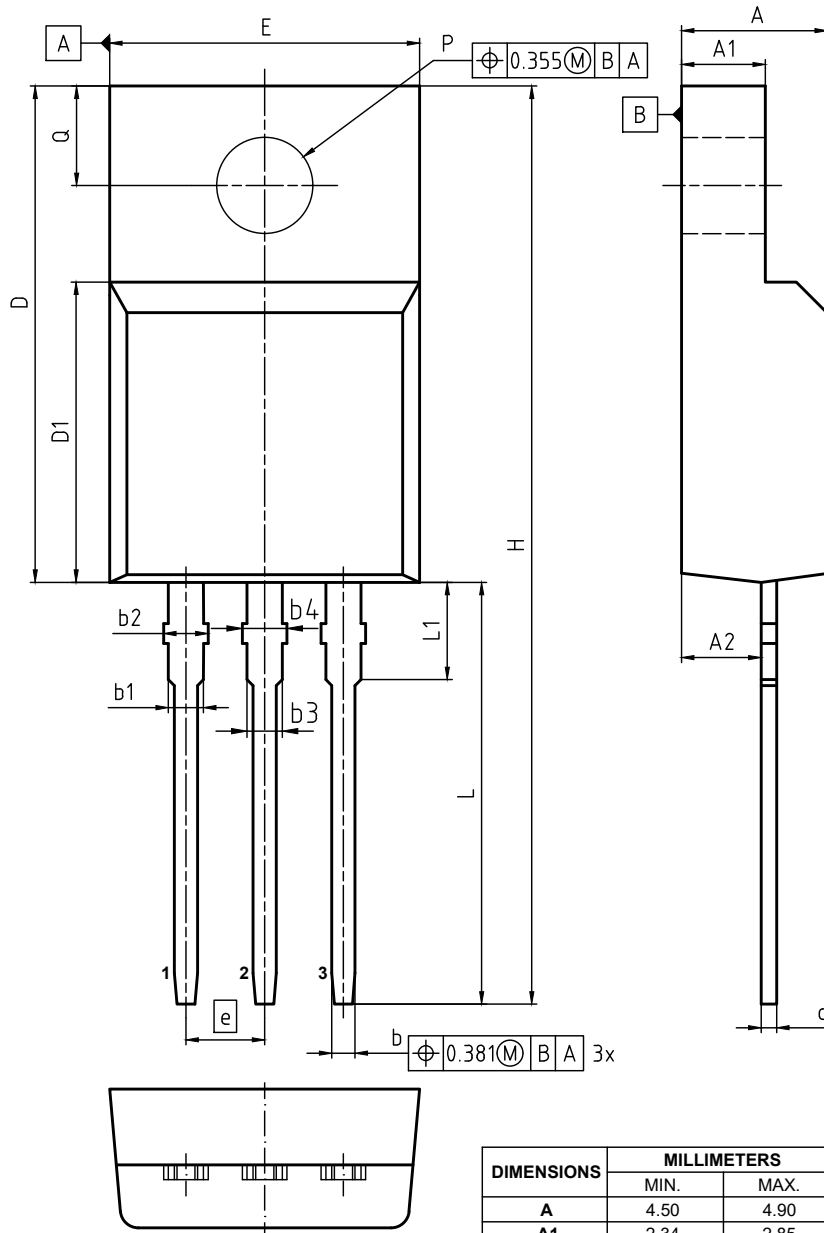
ALL DIMENSIONS REFER TO JEDEC STANDARD TO-252 AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

DIMENSION	MILLIMETERS	
	MIN.	MAX.
A	2.16	2.41
A1	0.00	0.15
b	0.64	0.89
b2	0.65	1.15
b3	4.95	5.50
c	0.46	0.61
c2	0.40	0.98
D	5.97	6.22
D1	5.02	5.84
E	6.35	6.73
E1	4.32	5.50
e	2.29	
e1	4.57	
N	3	
H	9.40	10.48
L	1.18	1.78
L3	0.89	1.27
L4	0.51	1.02

DOCUMENT NO. Z8B00003328
REVISION 07
SCALE: 10:1 0 1 2mm 
EUROPEAN PROJECTION 
ISSUE DATE 01.04.2020

**Figure 3 Outline PG-TO252-3, dimensions in mm/inches**

**600V CoolMOS™ P6 Power Transistor**  
**IPB60R380P6, IPP60R380P6, IPD60R380P6, IPA60R380P6**



NOTES:  
 DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS  
 GATE BURRS ARE LESS THAN 0.5 mm

DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	4.50	4.90
A1	2.34	2.85
A2	2.42	2.86
b	0.65	0.90
b1	0.95	1.38
b2	0.95	1.51
b3	0.65	1.38
b4	0.65	1.51
c	0.40	0.63
D	15.67	16.15
D1	8.97	9.83
E	10.00	10.65
e	2.54	
H	28.70	29.75
L	12.78	13.75
L1	2.83	3.45
øP	3.00	3.30
Q	3.15	3.50

<b>DOCUMENT NO.</b> Z8B00003319
<b>REVISION</b> 10
<b>ISSUE DATE</b> 21.03.2019
<b>SCALE 5:1</b> 0 1 2 3 4 5mm
<b>EUROPEAN PROJECTION</b> 

**Figure 4 Outline PG-T0220 FullPAK, dimensions in mm**

## 7 Appendix A

### Table 13 Related Links

- IFX CoolMOS™ P6 Webpage: [www.infineon.com](http://www.infineon.com)
- IFX CoolMOS™ P6 application note: [www.infineon.com](http://www.infineon.com)
- IFX CoolMOS™ P6 simulation model: [www.infineon.com](http://www.infineon.com)
- IFX Design tools: [www.infineon.com](http://www.infineon.com)

# 600V CoolMOS™ P6 Power Transistor

IPB60R380P6, IPP60R380P6, IPD60R380P6, IPA60R380P6

## Revision History

IPB60R380P6, IPP60R380P6, IPD60R380P6, IPA60R380P6

**Revision: 2020-06-09, Rev. 2.4**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2013-12-05	Release of final version
2.1	2013-12-05	Release of multi-package datasheet
2.2	2015-07-10	PG-TO 263 package added
2.3	2017-08-22	Updated TO220 Full PAK package drawing on page 16
2.4	2020-06-09	Update DPAK, FullPAK package drawing, symbol drawing

### Trademarks

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